

DDR2 SO DIMM

TE Internal #: 1612618-4 SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .362 in [9.2 mm], Right Angle Module Orientation, Surface Mount Mount, DDR2 SO DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: Double Data Rate (DDR) 2

Stack Height: 9.2 mm [.362 in]

Module Orientation: Right Angle

PCB Mounting Style: Surface Mount

Connector System: Cable-to-Board

All DDR2 SO DIMM Sockets (30)



Features

| Product ⁻ | Гуре | Features |
|----------------------|------------|-----------------|
| | J I | |

| DRAM Type | Double Data Rate (DDR) 2 |
|-----------------------------------|--------------------------|
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |
| Configuration Features | |
| Number of Bays | 2 |
| Center Key | None |
| Number of Keys | 1 |
| Module Orientation | Right Angle |
| Number of Positions | 200 |
| Number of Rows | 2 |
| Keying | Standard |

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| Electrical Characteristics | |
|-----------------------------------------------|-----------------|
| DRAM Voltage | 1.8 V |
| Signal Characteristics | |
| SGRAM Voltage | 1.8 V |
| Body Features | |
| Ejector Location | Both Ends |
| Latch Material | Stainless Steel |
| Latch Plating Material | Tin |
| Module Key Type | SGRAM |
| Ejector Type | Locking |
| Connector Profile | Ultra High |
| Contact Features | |
| Socket Style | SO DIMM |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Current Rating (Max) | .5 A |

| Socket | Туре |
|--------|------|
|--------|------|

Memory Card

| Termination Features | |
|--------------------------|--------------------------------|
| Insertion Style | Cam-In |
| Mechanical Attachment | |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | .6 mm[.024 in] |
| Housing Color | Black |
| Housing Material | High Temperature Thermoplastic |
| Dimensions | |
| Stack Height | 9.2 mm[.362 in] |

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| Row-to-Row Spacing | 6.2 mm[.244 in] |
|-----------------------------|------------------------------------------------|
| Usage Conditions | |
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
| Operation/Application | |
| Circuit Application | Power |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Method | Semi-Hard Tray Assembly |
| Packaging Quantity | 20 |
| Other | |
| Comment | Semi-Hard Tray with 20 sockets PN 1279284-1 |
| | |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU ELV Directive 2000/53/EC | Compliant |
|-----------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------|
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 245°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

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on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series DDR2 SO DIMM



Customers Also Bought





Documents

Product Drawings

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SEMI-HARD TRAY DDR2 SODIMM SOCKET 200P 9

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1612618-4_E2.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1612618-4_E2.3d_igs.zip

English

Customer View Model ENG_CVM_CVM_1612618-4_E2.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

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English

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English

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